Claims

[Claim 1]

A polysilicon fractured product comprising:

fractured pieces having a ridge portion generated by fracturing a polysilicon rod, wherein

an average radius of curvature (r) at a tip end of a ridge portion having an angle of 70° or less of the fractured pieces is 60 μm or more.

[Claim 2]

The polysilicon fractured product according to claim 1, wherein

an average particle diameter is 20 mm to 100 mm.

[Claim 3]

A polysilicon package filled with the polysilicon fractured product according to claim 1 in a resin bag.

[Claim 4]

A polysilicon package filled with the polysilicon fractured product according to claim 2 in a resin bag.

[Claim 5]

A method for producing the polysilicon fractured product claimed in claim 1, comprising:

a fracturing step of fracturing a polysilicon rod to obtain fractured pieces; and

an etching step of performing etching at an etching speed of 1.1 μm/min to 2.5 μm/min to achieve an etching depth of 5 μm or more by immersing the fractured pieces obtained in the fracturing step in an etching solution which is a mixed acid aqueous solution containing 0.5% by mass to 10% by mass of hydrofluoric acid and 48% by mass to 68% by mass of nitric acid at 15°C to 30°C, with the proviso that the etching solution does not contain surfactant.